



Title of Change:	Lead Finish and BOM change for DFN/QFN products assembled at Seremban, Malaysia – Group 2													
Proposed first ship date:	26 November 2016 or earlier upon customer approval													
Contact information:	Contact your local ON Semiconductor Sales Office or <alan.garlington@onsemi.com>													
Samples:	Contact your local ON Semiconductor Sales Office or <KokInn.Hoo@onsemi.com>													
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <KokInn.Hoo@onsemi.com>													
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.													
Change Part Identification:	Parts can be identified by the marking part number and date code once the change is implemented into production.													
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____													
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Change/Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____													
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Seremban, Malaysia <input type="checkbox"/> External Foundry/Subcon site(s)													
Description and Purpose:	<p>This is the Final notice for the next groups (group 2) of devices which will be converted to use a new Lead Frame using a PPF lead finish along with a new die attach epoxy and mold compound. The Lead Frame will be changing from a Matte Tin lead finish to a PPF finish consisting of Ni-Pd-Au. All new materials will be fully qualified prior to issuing the Final Product Change notice to customers.</p> <table border="1"> <thead> <tr> <th>Material to be changed</th> <th>Before Change Description</th> <th>After Change Description</th> </tr> </thead> <tbody> <tr> <td>Lead Frame</td> <td>C194 Copper with Pure Tin Plating</td> <td>C194 Copper with Ni-Pd-Au Plated Frame (PPF)</td> </tr> <tr> <td>Die Attach Epoxy</td> <td>SR4</td> <td>CRM1084P</td> </tr> <tr> <td>Mold Compound</td> <td>EME-G760</td> <td>EME-G770</td> </tr> </tbody> </table>		Material to be changed	Before Change Description	After Change Description	Lead Frame	C194 Copper with Pure Tin Plating	C194 Copper with Ni-Pd-Au Plated Frame (PPF)	Die Attach Epoxy	SR4	CRM1084P	Mold Compound	EME-G760	EME-G770
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	<p>The Initial Notice (IPC21306X) was published 27 April 2016 as the initial notification for this change.</p> <p>For reference: FPCN # 20948X was issued on 7/10/2015 for the first group of parts with this change.</p>													

**Reliability Data Summary:**

QV DEVICE NAME : NCP1031MNTXG
 PACKAGE : DFN 8 4x4x.9

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	0/270
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/270
TC	JESD22-A104	Ta= -65°C to +150°C	1000 cyc	0/270
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/270
AC	JESD22-A102	121°C, 100% RH, 15psig	96 hrs	0/270
SD	JSTD002	Ta = 245C, 10 sec		0/ 45

Electrical Characteristic Summary:

There is no change to electrical characteristics. There is no change to Data sheet parameters or performance.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
ESD8024MNTAG	NCP1031MNTXG
NB100LVEP56MNG	NCP1031MNTXG
NB100LVEP91MNG	NCP1031MNTXG
NB3H83905CMNG	NCP1031MNTXG
NB3N106KMNG	NCP1031MNTXG
NB3N106KMNR2G	NCP1031MNTXG
NB7VQ1006MMNG	NCP1031MNTXG
NB7VQ1006MMNTXG	NCP1031MNTXG
NCN5150MNTWG	NCP1031MNTXG
NCN8025AMNTXG	NCP1031MNTXG
NCN8026AMNTXG	NCP1031MNTXG
NCP3063BMNTXG	NCP1031MNTXG
NCP3063MNTXG	NCP1031MNTXG
NCP3064BMNTXG	NCP1031MNTXG
NCP3064MNTXG	NCP1031MNTXG
NCP3065MNTXG	NCP1031MNTXG
NCP3066MNTXG	NCP1031MNTXG
NCP4303AMNTWG	NCP1031MNTXG
NCP4304AMNTWG	NCP1031MNTXG
NCP4304BMNTWG	NCP1031MNTXG
NCP5662MN15R2G	NCP1031MNTXG



NCP5662MN33R2G	NCP1031MNTXG
NCP5662MNADJR2G	NCP1031MNTXG
NCP59151MN50TYG	NCP1031MNTXG
NCP59152MNADJTYG	NCP1031MNTXG
NCS5651MNTXG	NCP1031MNTXG
NCT7491MNTXG	NCP1031MNTXG
NB100LVEP17MNG	NCP1031MNTXG
NB100LVEP17MNR2G	NCP1031MNTXG
NB100LVEP56MNR2G	NCP1031MNTXG
NB100LVEP91MNR2G	NCP1031MNTXG
NB3H83905CMNTXG	NCP1031MNTXG
NB6L295MMNG	NCP1031MNTXG
NB6L295MMNTXG	NCP1031MNTXG

List of Affected Customer Specific Part:

NOTE: Please be informed that parts impacted by this PDN/PCN are Special/Customer specific parts, thus MPN & CPN info will be available to affected customers only by clicking the "[Custom PCN for Selected Company Button](#)" in the Document Analysis page of PCMS/PCN Alert.